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PCB Artwork Request

This form defines most of the criteria and considerations required when creating artwork for a PCB.
Please complete the following with as much applicable information as possible.

Return completed forms to Sabrina Beck at sbeck@altekcompany.com or the address listed above.

Project Information:

Customer Name: _____
Project Name/Description: _____
Assembly P/N: _____ Rev: _____
Bare PCB P/N: _____ Rev: _____

Primary Design Input: *(Check off if item will be provided)*

- Dimensioned board outline drawing (with all appropriate tolerances) including:
 - Mounting holes
 - Height restrictions
 - Connectors
 - Tooling holes
 - Critical component locations
 - Restricted areas (hardware, heatsinks, etc)
 - Fiducials
 - Edge clearance
 - Special features
- Schematic diagram.
- Bill of materials (manufacturer, P/N, and reference designators matching the schematic symbols)
- Component part library (cross reference schematic symbols to pcb footprints).
- CAD software specific files (eg. Cadstar files: .cdo, .sch, .pcb, .col, .sel, .sym, .cmp, .lib)

(Complete all fields)

Board Type: Rigid Flex Rigid-Flex combination
Board Material (FR4, clad, epoxy, etc.): _____
Board Thickness: _____
Conductor Finish: Lead HASL Lead Free HASL Immersion Silver Immersion Gold (ENIG)
 Other: _____
Surface Finish: SMOBC None Other: _____
Select one: Through-Hole Surface Mount Mixed technology
Component placement: Not Restricted Fixed (If fixed must submit drawing.)
Component orientation requirements: _____
Are connector pin assignments fixed: Yes No
Are gate/pin swapping allowed: Yes No
Thieving allowed for copper balance: Yes No
Are parts allowed on both sides: Never If necessary Only in certain areas (provide dwg)

Test Considerations: *(Complete fields where applicable)*

Test point requirements: _____
 ICT requirements: _____
 HiPot requirements: _____
 Shock/Vibe requirements: _____

Design Technology: *(Complete fields where applicable)*

Special plane requirements: _____
 Special ground pattern requirements: _____
 Mounting hole connections (ground, specific nets): _____
 Minimum via size (signal, power): _____
 Clearance of traces to board outline: _____
 Clearance of components to board outline: _____
 Pastemask clearance requirements: _____
 Creepage and clearance requirements: _____
 Trace width/clearance requirements: _____
 Heat sinking areas or requirements: _____

Check off if specified item is in design.

<input type="checkbox"/> Micro vias	<input type="checkbox"/> Blind vias	<input type="checkbox"/> Plugged vias	<input type="checkbox"/> Buried vias
<input type="checkbox"/> HDI	<input type="checkbox"/> BGA	<input type="checkbox"/> Fine-pitch components	

Other special technologies: _____

Solder Mask: *(Complete fields where applicable)*

Sides: Top Bottom Both
 Color: _____
 Special clearance requirements: _____
 Tented vias: Yes No

Special Considerations: *(Complete fields where applicable)*

Hole plating requirements: _____
 Controlled impedance requirements: _____
 Routing requirements: _____
 Trace requirements (eg. corner types, 90/45 degree, radial): _____
 High voltage requirements: _____
 High current requirements: _____
 High speed requirements: _____
 RF requirements: _____
 Panel requirements: _____

